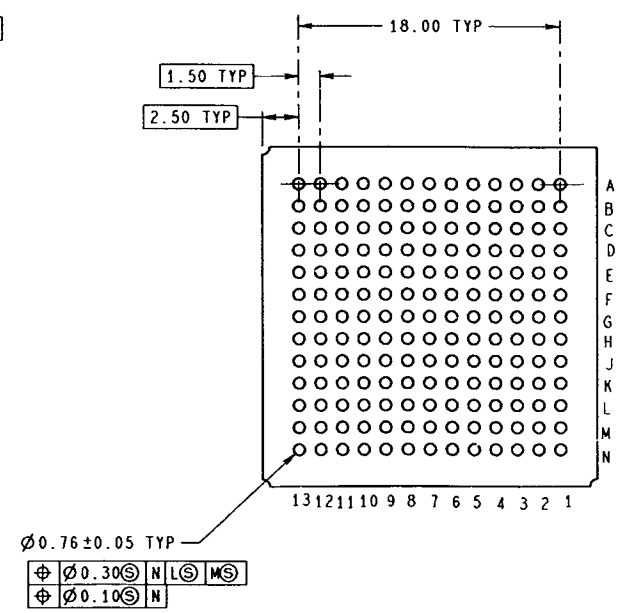
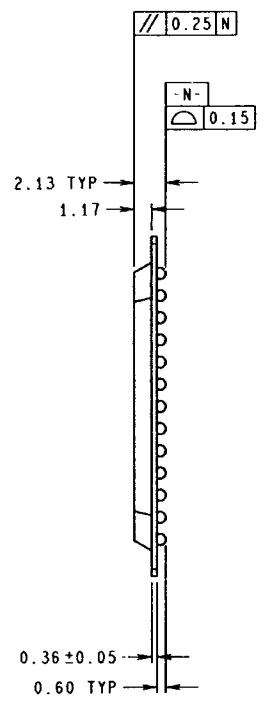
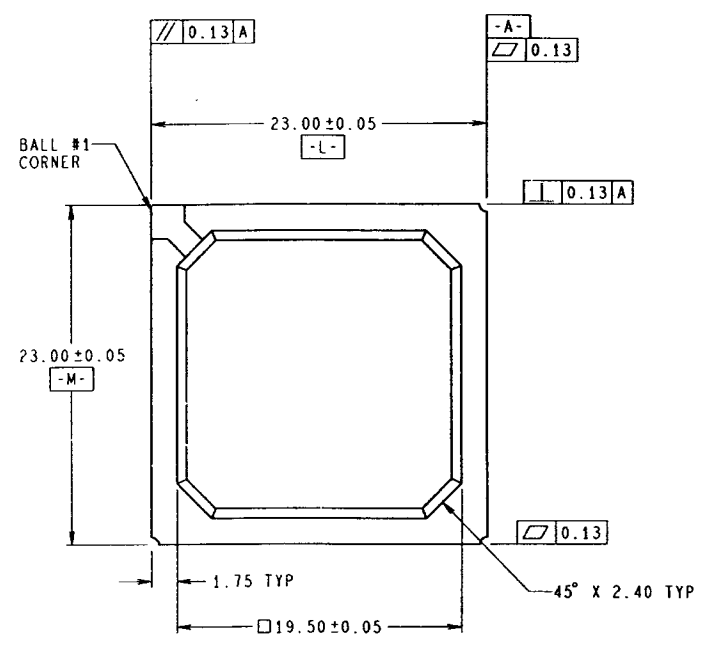


REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL.	10387	07/21/94	DEG/SZ



DIMENSIONS ARE IN MILLIMETERS

- NOTES: UNLESS OTHERWISE SPECIFIED
- SOLDER BALL COMPOSITION: Sn 63%, Pb 37%.
 - REFERENCE JEDEC REGISTRATION MO-151 VARIATION -1.50 PITCH, DATED 11-93.

APPROVALS		DATE	NATIONAL SEMICONDUCTOR CORPORATION			
DESN	D.E. Grady	07/21/94	2900 Semiconductor Drive, Santa Clara, CA 95052-8090			
DTG. CBL.		01/19/94	PLASTIC BALL GRID ARRAY, 169 TERMINAL, 1.50mm PITCH			
APP'D	<i>[Signature]</i>	8-1-94				
PROJECTION			SCALE	SIZE	DRAWING NUMBER	REV
			N/A	C	MKT-UDA169A	A
			DO NOT SCALE DRAWING		SHEET 1 of 1	